Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	05/28/2022

Details for "BQ27220YZFT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
BQ27220YZFT	SNAGCU	Level-1-260C-UNLIM	TI PHILIPPINES CLARK A/T	YZF 9	1.62x1.66x.279	2.5

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Back Side Coating	ack Side Coating						
Other Inorganic Materials	Silica	7631-86-9	0.097736	55.066879	550669	3.951883	39519
Other Plastics and Rubber	Carbon Black	1333-86-4	0.003003	1.691964	16920	0.121424	1214
Other Plastics and Rubber	Imidazole Derivative	288-32-4	0.000667	0.375804	3758	0.02697	270
Thermoplastics	Epoxy	85954-11-6	0.07608	42.865353	428654	3.076239	30762
Sub-Total			0.177486	100	1000000	7.176516	71765
Semiconductor Device	*	*					
Ceramics / Glass	Doped Silicon	7440-21-3	1.747418	100	1000000	70.655561	706556
Sub-Total			1.747418	100	1000000	70.655561	706556
Solder Bump							
Copper and Its Alloys	Copper	7440-50-8	0.002741	0.499958	5000	0.11083	1108
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.523575	95.500013	955000	21.17037	211704
Precious Metals	Silver	7440-22-4	0.02193	4.000029	40000	0.886723	8867
Sub-Total			0.548246	100	1000000	22.167923	221679
Total			2.47315			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The pure calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU ROHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI as is. For additional information, please contact TI customer sup

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/28/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szq088

Green: Means the content of Chlorine (CI) and Bromine (Br}-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.